

Vishay Siliconix

RoHS

COMPLIANT

N-Channel 75-V (D-S) MOSFET

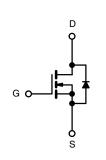
PRODUCT	SUMMARY		
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)	Q _g (Typ.)
75	0.0068 at V_{GS} = 10 V	90 ^d	75

FEATURES

- TrenchFET[®] Power MOSFET
- 175 °C Junction Temperature
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Power Supply
- Secondary Synchronous Rectification
- Industrial



N-Channel MOSFET

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Top View

Ordering Information	SUP90N08-6m8P-E3 (Lead (Pb)-free)
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ABSOLUTE MAXIMUM RATINGS	T _C = 25 °C, unless oth	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	75	V	
Gate-Source Voltage		V _{GS}	± 22	- V	
Continuous Drain Current ($T_1 = 175 ^{\circ}C$)	T _C = 25 °C	1-	90 ^d		
Continuous Drain Current $(1) = 175^{\circ}$ C)	T _C = 70 °C	I _D	90 ^d	A	
Pulsed Drain Current		I _{DM}	240	^	
Avalanche Current		I _{AS}	50		
Single Avalanche Energy ^a L = 0.1 mH		E _{AS}	125	mJ	
	T _C = 25 °C	Р	272 ^b	14/	
Maximum Power Dissipation ^a	T _A = 25 °C ^c	– P _D –	3.75	W	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	40	°C/W
Junction-to-Case (Drain)	R _{thJC}	0.55	0/11

Notes:

a. Duty cycle \leq 1 %.

b. See SOA curve for voltage derating.c. When Mounted on 1" square PCB (FR-4 material).

d. Package limited.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	75			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2.5		4.5	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 250	nA	
		$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}$		1			
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 75 V, V_{GS} = 0 V, T_{J} = 125 °C			50	50 μΑ	
		$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	70			Α	
	Б	V _{GS} = 10 V, I _D = 20 A		0.0056	0.0068	0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V_{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.009	0.011	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		50		S	
Dynamic ^b	•			•			
Input Capacitance	C _{iss}			4620			
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 30 V, f = 1 MHz		517		pF	
Reverse Transfer Capacitance	C _{rss}			247		- P -	
Total Gate Charge ^c	Qg			75	115		
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 30 V, V_{GS} = 10 V, I_D = 50 A		25.5		nC	
Gate-Drain Charge ^c	Q _{gd}			20			
Gate Resistance	R _g	f = 1 MHz		1.2	2.4	Ω	
Turn-On Delay Time ^c	t _{d(on)}			16	30		
Rise Time ^c	t _r	V_{DD} = 30 V, R_L = 0.6 Ω		11	20	-	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, \text{ V}_{\text{GEN}} = 10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		24	40	- ns	
Fall Time ^c	t _f		10 2		20		
Source-Drain Diode Ratings and Cha	aracteristics 7	_C = 25 °C ^b					
Continuous Current	۱ _S				85		
Pulsed Current	I _{SM}				240	A	
Forward Voltage ^a	V _{SD}	$I_{F} = 20 \text{ A}, V_{GS} = 0 \text{ V}$		0.83	1.5	V	
Reverse Recovery Time	t _{rr}			60	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = 75 A, dl/dt = 100 A/μs		3.3	4.5	Α	
Reverse Recovery Charge	Q _{rr}			100	150	nC	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

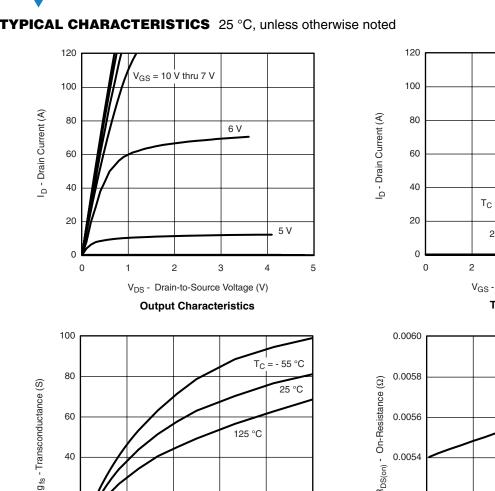
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



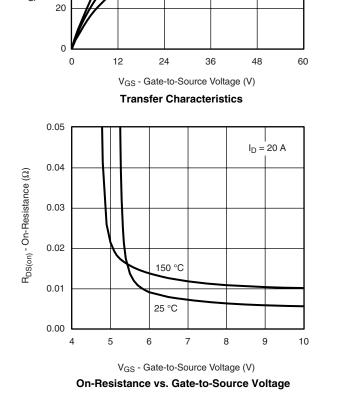
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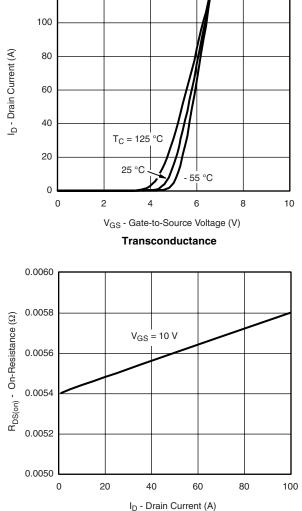
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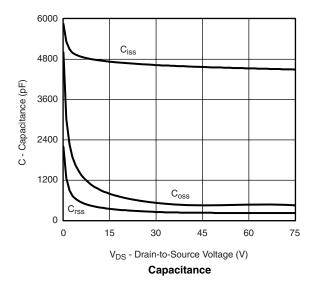
125 °C

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





On-Resistance vs. Drain Current



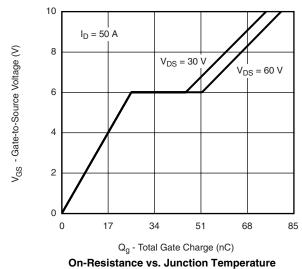
Document Number: 69538 S09-2435-Rev. C, 16-Nov-09

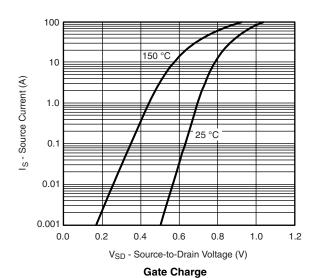
60

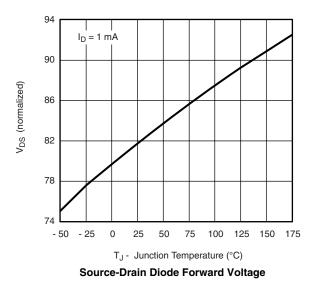
40

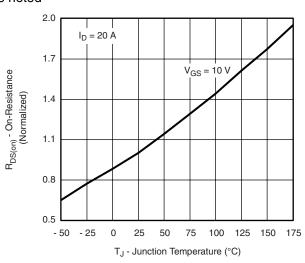
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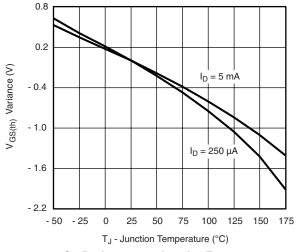




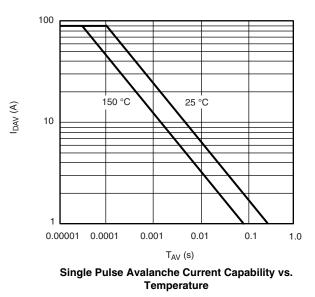


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On-Resistance vs. Junction Temperature

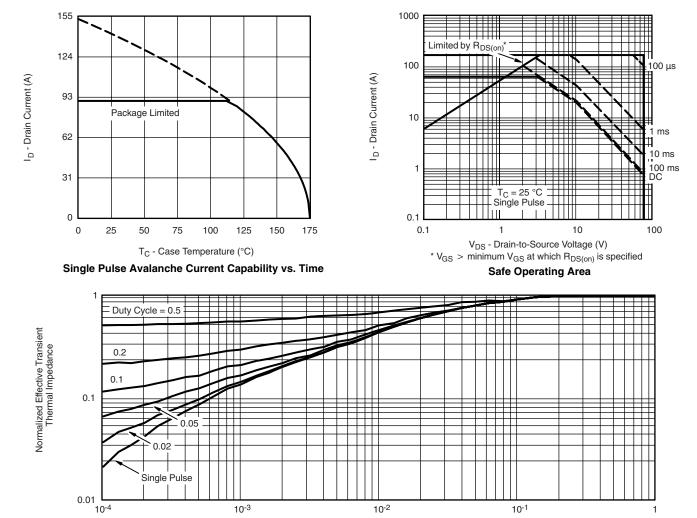


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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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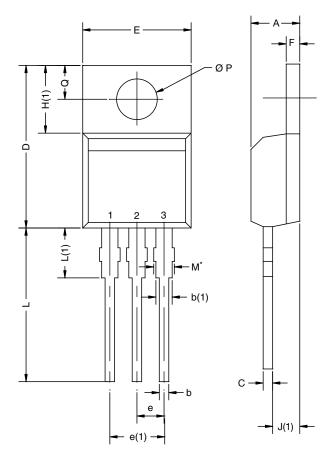
Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg269538.



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TO-220AB

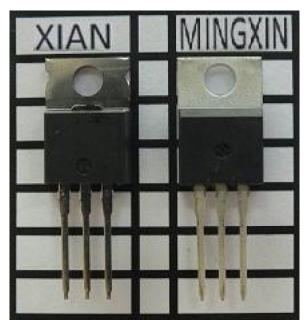


	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
E	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

Notes

 * M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM

Xi'an and Mingxin actual photo



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